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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	18
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f687t-i-so

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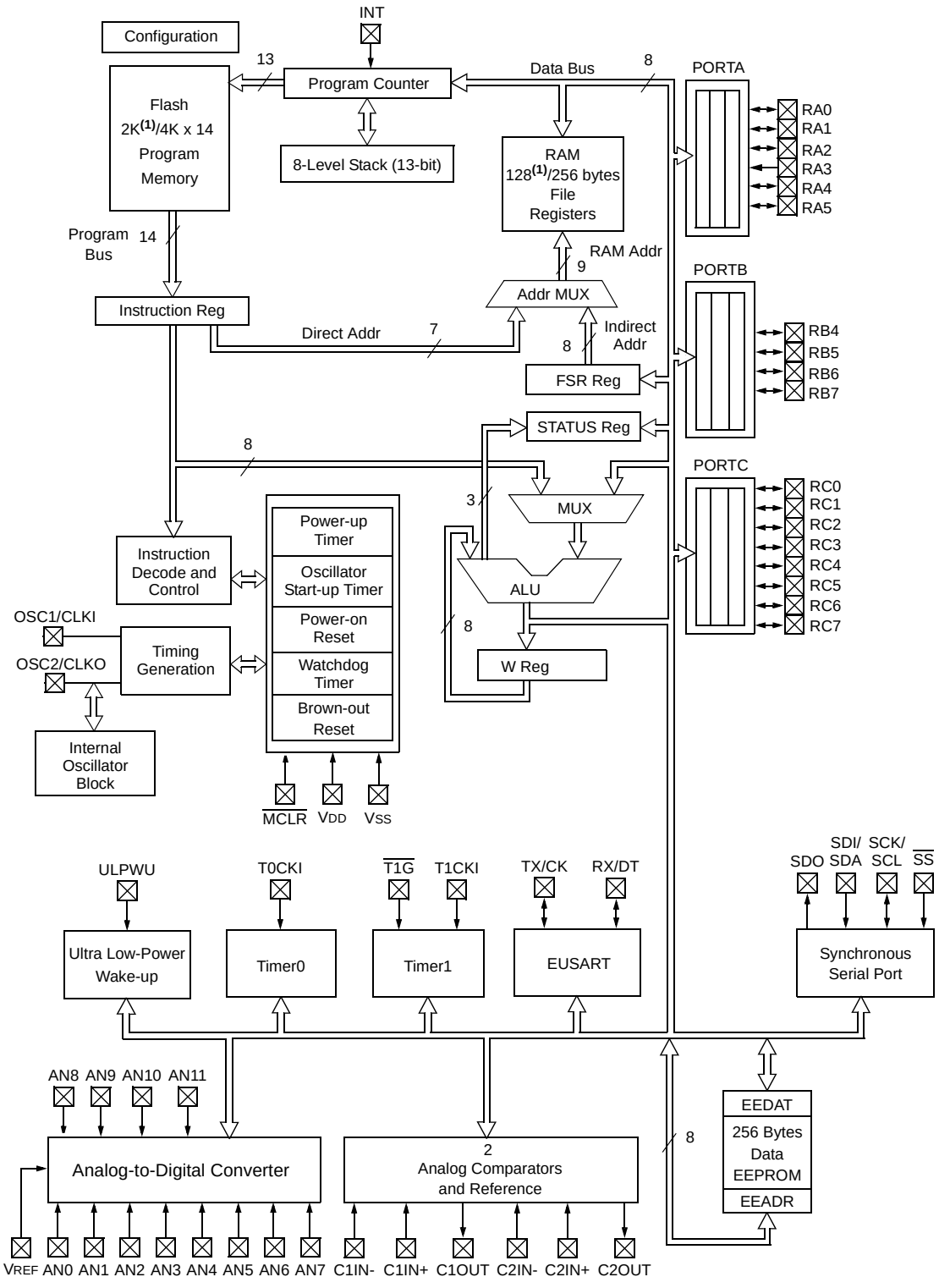
FIGURE 1-4: PIC16F687/PIC16F689 BLOCK DIAGRAM



Note 1: PIC16F687 only.

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TABLE 1-1: PINOUT DESCRIPTION – PIC16F631

Name	Function	Input Type	Output Type	Description
RA0/C1IN+/ICSPDAT/ULPWU	RA0	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	C1IN+	AN	—	Comparator C1 non-inverting input.
	ICSPDAT	ST	CMOS	ICSP™ Data I/O.
	ULPWU	AN	—	Ultra Low-Power Wake-up input.
RA1/C12IN0-/ICSPCLK	RA1	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	C12IN0-	AN	—	Comparator C1 or C2 inverting input.
	ICSPCLK	ST	—	ICSP™ clock.
RA2/T0CKI/INT/C1OUT	RA2	ST	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	T0CKI	ST	—	Timer0 clock input.
	INT	ST	—	External interrupt pin.
	C1OUT	—	CMOS	Comparator C1 output.
RA3/$\overline{\text{MCLR}}$/V_{PP}	RA3	TTL	—	General purpose input. Individually controlled interrupt-on-change.
	$\overline{\text{MCLR}}$	ST	—	Master Clear with internal pull-up.
	V_{PP}	HV	—	Programming voltage.
RA4/$\overline{\text{T1G}}$/OSC2/CLKOUT	RA4	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	$\overline{\text{T1G}}$	ST	—	Timer1 gate input.
	OSC2	—	XTAL	Crystal/Resonator.
	CLKOUT	—	CMOS	F_{OSC}/4 output.
RA5/T1CKI/OSC1/CLKIN	RA5	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	T1CKI	ST	—	Timer1 clock input.
	OSC1	XTAL	—	Crystal/Resonator.
	CLKIN	ST	—	External clock input/RC oscillator connection.
RB4	RB4	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
RB5	RB5	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
RB6	RB6	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
RB7	RB7	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
RC0/C2IN+	RC0	ST	CMOS	General purpose I/O.
	C2IN+	AN	—	Comparator C2 non-inverting input.
RC1/C12IN1-	RC1	ST	CMOS	General purpose I/O.
	C12IN1-	AN	—	Comparator C1 or C2 inverting input.
RC2/C12IN2-	RC2	ST	CMOS	General purpose I/O.
	C12IN2-	AN	—	Comparator C1 or C2 inverting input.
RC3/C12IN3-	RC3	ST	CMOS	General purpose I/O.
	C12IN3-	AN	—	Comparator C1 or C2 inverting input.
RC4/C2OUT	RC4	ST	CMOS	General purpose I/O.
	C2OUT	—	CMOS	Comparator C2 output.
RC5	RC5	ST	CMOS	General purpose I/O.

Legend: AN = Analog input or output; CMOS=CMOS compatible input or output
TTL = TTL compatible input; ST= Schmitt Trigger input with CMOS levels
HV = High Voltage; XTAL= Crystal

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TABLE 1-4: PINOUT DESCRIPTION – PIC16F687/PIC16F689 (CONTINUED)

Name	Function	Input Type	Output Type	Description
RB6/SCK/SCL	RB6	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	SCK	ST	CMOS	SPI clock.
	SCL	ST	OD	I^2C™ clock.
RB7/TX/CK	RB7	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	TX	—	CMOS	EUSART asynchronous output.
	CK	ST	CMOS	EUSART synchronous clock.
RC0/AN4/C2IN+	RC0	ST	CMOS	General purpose I/O.
	AN4	AN	—	A/D Channel 4 input.
	C2IN+	AN	—	Comparator C2 positive input.
RC1/AN5/C12IN1-	RC1	ST	CMOS	General purpose I/O.
	AN5	AN	—	A/D Channel 5 input.
	C12IN1-	AN	—	Comparator C1 or C2 negative input.
RC2/AN6/C12IN2-	RC2	ST	CMOS	General purpose I/O.
	AN6	AN	—	A/D Channel 6 input.
	C12IN2-	AN	—	Comparator C1 or C2 negative input.
RC3/AN7/C12IN3-	RC3	ST	CMOS	General purpose I/O.
	AN7	AN	—	A/D Channel 7 input.
	C12IN3-	AN	—	Comparator C1 or C2 negative input.
RC4/C2OUT	RC4	ST	CMOS	General purpose I/O.
	C2OUT	—	CMOS	Comparator C2 output.
RC5	RC5	ST	CMOS	General purpose I/O.
RC6/AN8/$\overline{SS}$	RC6	ST	CMOS	General purpose I/O.
	AN8	AN	—	A/D Channel 8 input.
	$\overline{SS}$	ST	—	Slave Select input.
RC7/AN9/SDO	RC7	ST	CMOS	General purpose I/O.
	AN9	AN	—	A/D Channel 9 input.
	SDO	—	CMOS	SPI data output.
VSS	VSS	Power	—	Ground reference.
VDD	VDD	Power	—	Positive supply.

Legend: AN = Analog input or output CMOS=CMOS compatible input or outputOD= Open Drain
TTL = TTL compatible input ST= Schmitt Trigger input with CMOS levels
HV = High Voltage XTAL= Crystal

3.0 OSCILLATOR MODULE (WITH FAIL-SAFE CLOCK MONITOR)

3.1 Overview

The Oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 3-1 illustrates a block diagram of the Oscillator module.

Clock sources can be configured from external oscillators, quartz crystal resonators, ceramic resonators and Resistor-Capacitor (RC) circuits. In addition, the system clock source can be configured from one of two internal oscillators, with a choice of speeds selectable via software. Additional clock features include:

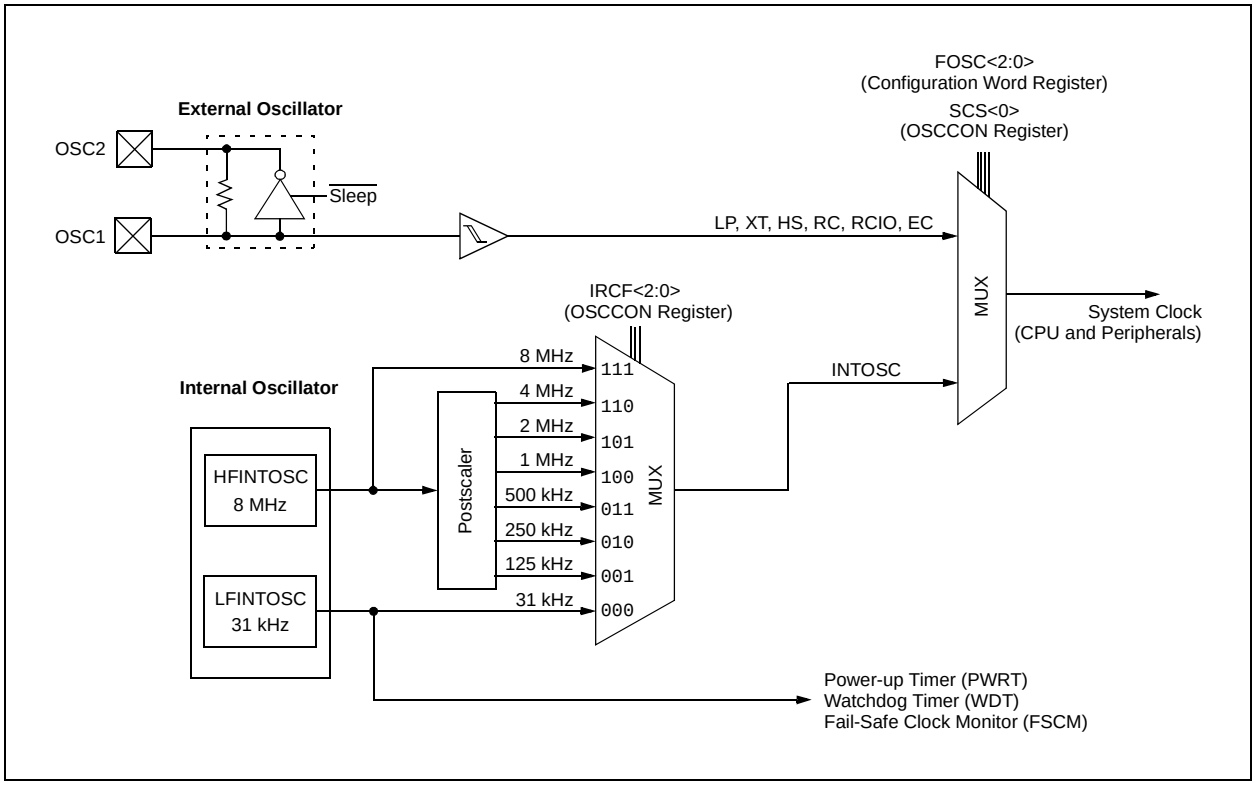
- Selectable system clock source between external or internal via software.
- Two-Speed Start-up mode, which minimizes latency between external oscillator start-up and code execution.
- Fail-Safe Clock Monitor (FSCM) designed to detect a failure of the external clock source (LP, XT, HS, EC or RC modes) and switch automatically to the internal oscillator.

The Oscillator module can be configured in one of eight clock modes.

1. EC – External clock with I/O on OSC2/CLKOUT.
2. LP – 32 kHz Low-Power Crystal mode.
3. XT – Medium Gain Crystal or Ceramic Resonator Oscillator mode.
4. HS – High Gain Crystal or Ceramic Resonator mode.
5. RC – External Resistor-Capacitor (RC) with FOSC/4 output on OSC2/CLKOUT.
6. RCIO – External Resistor-Capacitor (RC) with I/O on OSC2/CLKOUT.
7. INTOSC – Internal oscillator with FOSC/4 output on OSC2 and I/O on OSC1/CLKIN.
8. INTOSCIO – Internal oscillator with I/O on OSC1/CLKIN and OSC2/CLKOUT.

Clock Source modes are configured by the FOSC<2:0> bits in the Configuration Word register (CONFIG). The internal clock can be generated from two internal oscillators. The HFINTOSC is a calibrated high-frequency oscillator. The LFINTOSC is an uncalibrated low-frequency oscillator.

FIGURE 3-1: SIMPLIFIED PIC® MCU CLOCK SOURCE BLOCK DIAGRAM

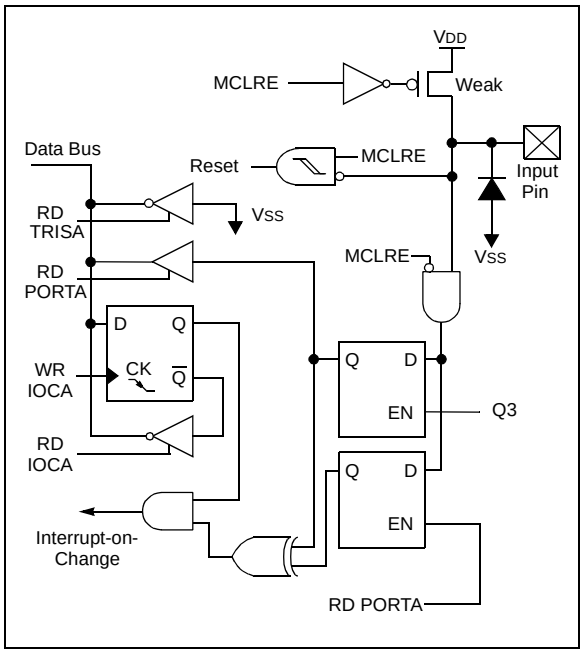


4.2.5.4 RA3/$\overline{MCLR}$/VPP

Figure 4-4 shows the diagram for this pin. The RA3/$\overline{MCLR}$/VPP pin is configurable to function as one of the following:

- a general purpose input
- as Master Clear Reset with weak pull-up

FIGURE 4-4: BLOCK DIAGRAM OF RA3

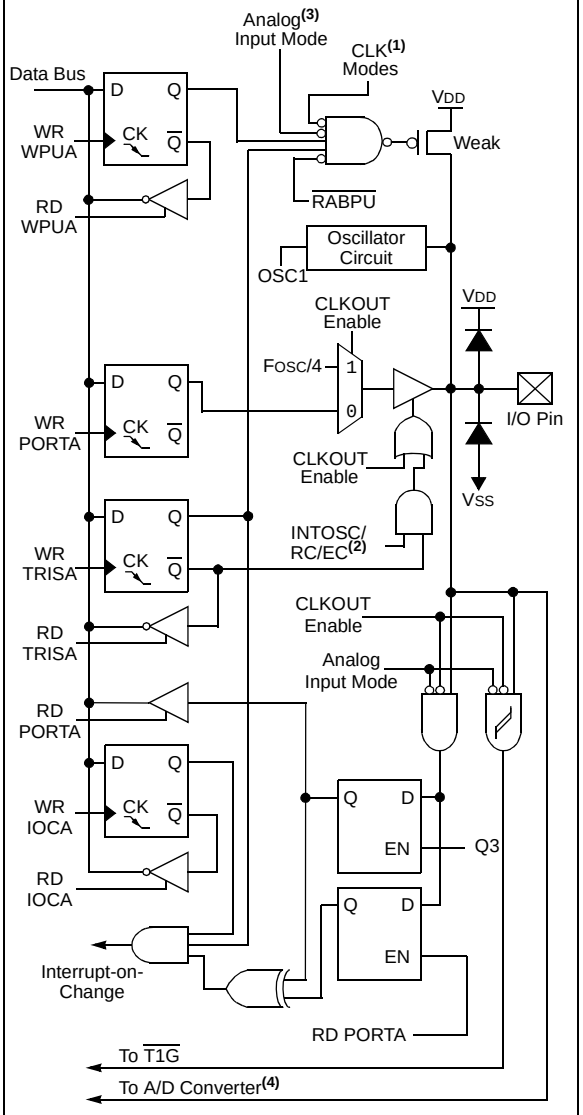


4.2.5.5 RA4/AN3/$\overline{T1G}$/OSC2/CLKOUT

Figure 4-5 shows the diagram for this pin. The RA4/AN3/$\overline{T1G}$/OSC2/CLKOUT pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the ADC (except PIC16F631)
- a Timer1 gate input
- a crystal/resonator connection
- a clock output

FIGURE 4-5: BLOCK DIAGRAM OF RA4



Note 1: CLK modes are XT, HS, LP, LPTMR1 and CLKOUT Enable.

2: With CLKOUT option.

3: ANSEL determines Analog Input mode.

4: Not implemented on PIC16F631.

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4.4.3.4 RB7/TX/CK

Figure 4-10 shows the diagram for this pin. The RB7/TX/CK[(1)] pin is configurable to function as one of the following:

- a general purpose I/O
- an asynchronous serial output
- a synchronous clock I/O

Note 1: TX and CK are available on PIC16F687/PIC16F689/PIC16F690 only.

FIGURE 4-10: BLOCK DIAGRAM OF RB7

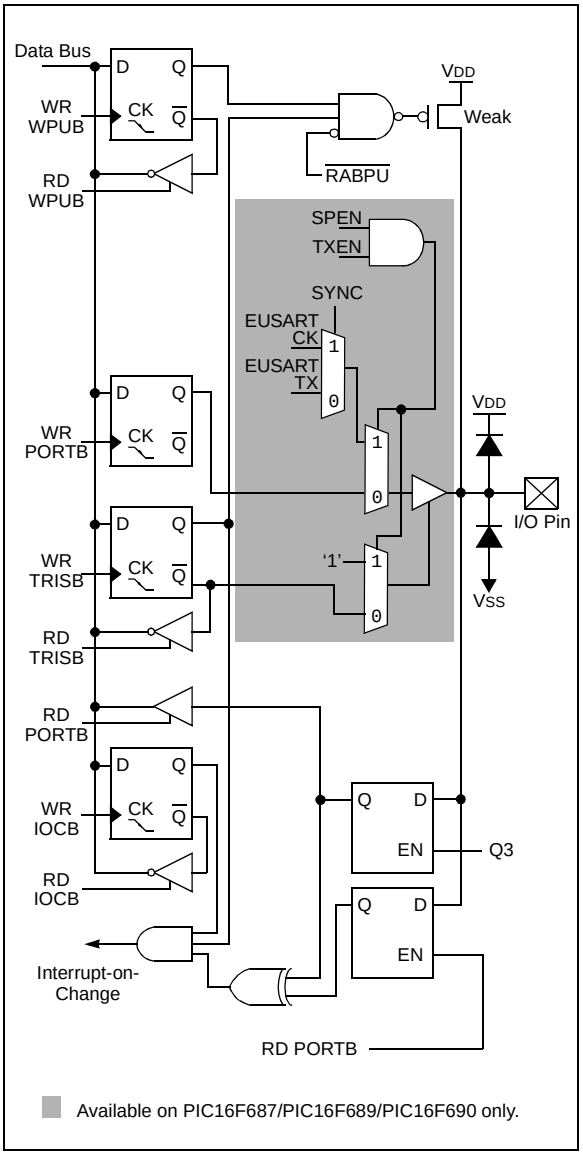

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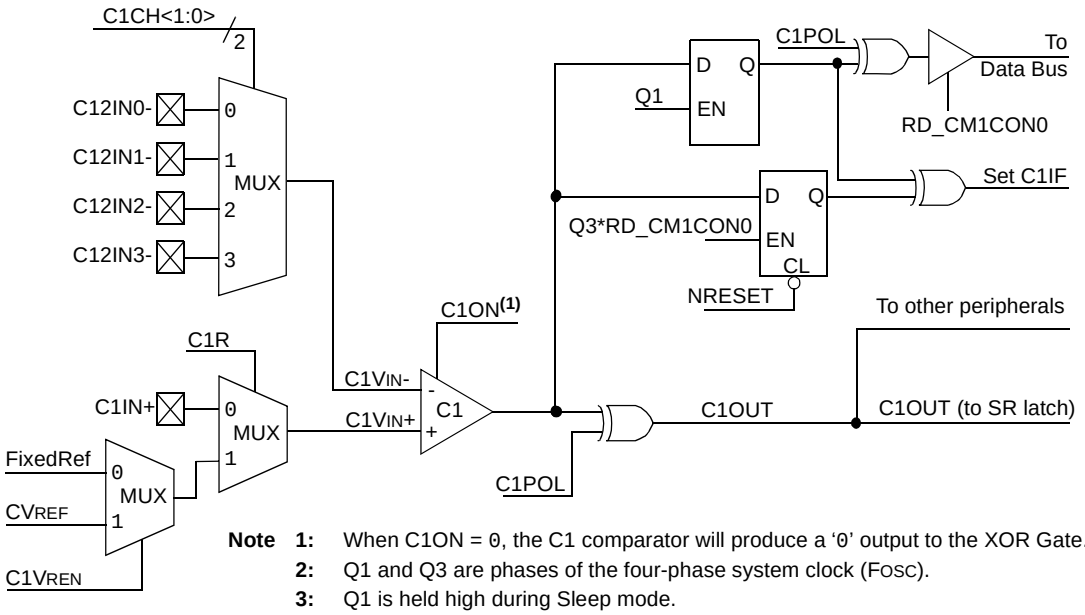
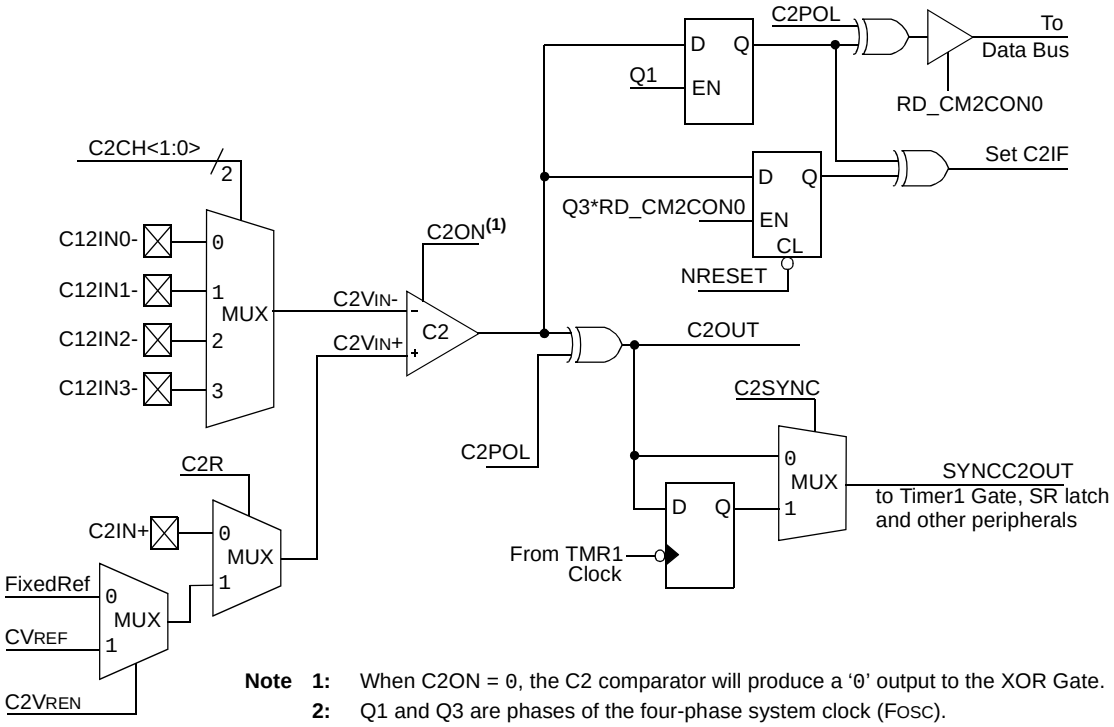
FIGURE 8-2: COMPARATOR C1 SIMPLIFIED BLOCK DIAGRAM



Note 1: When C1ON = 0, the C1 comparator will produce a '0' output to the XOR Gate.
2: Q1 and Q3 are phases of the four-phase system clock (FOSC).
3: Q1 is held high during Sleep mode.

FIGURE 8-3: COMPARATOR C2 SIMPLIFIED BLOCK DIAGRAM



Note 1: When C2ON = 0, the C2 comparator will produce a '0' output to the XOR Gate.
2: Q1 and Q3 are phases of the four-phase system clock (FOSC).
3: Q1 is held high during Sleep mode.

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9.2 ADC Operation

9.2.1 STARTING A CONVERSION

To enable the ADC module, the ADON bit of the ADCON0 register must be set to a '1'. Setting the GO/DONE bit of the ADCON0 register to a '1' will start the Analog-to-Digital conversion.

Note:	The GO/DONE bit should not be set in the same instruction that turns on the ADC. Refer to **Section 9.2.6 "A/D Conversion Procedure"**.

9.2.2 COMPLETION OF A CONVERSION

When the conversion is complete, the ADC module will:

- Clear the GO/DONE bit
- Set the ADIF flag bit
- Update the ADRESH:ADRESL registers with new conversion result

9.2.3 TERMINATING A CONVERSION

If a conversion must be terminated before completion, the GO/DONE bit can be cleared in software. The ADRESH:ADRESL registers will not be updated with the partially complete Analog-to-Digital conversion sample. Instead, the ADRESH:ADRESL register pair will retain the value of the previous conversion. Additionally, a 2 TAD delay is required before another acquisition can be initiated. Following this delay, an input acquisition is automatically started on the selected channel.

Note:	A device Reset forces all registers to their Reset state. Thus, the ADC module is turned off and any pending conversion is terminated.

9.2.4 ADC OPERATION DURING SLEEP

The ADC module can operate during Sleep. This requires the ADC clock source to be set to the FRC option. When the FRC clock source is selected, the ADC waits one additional instruction before starting the conversion. This allows the SLEEP instruction to be executed, which can reduce system noise during the conversion. If the ADC interrupt is enabled, the device will wake-up from Sleep when the conversion completes. If the ADC interrupt is disabled, the ADC module is turned off after the conversion completes, although the ADON bit remains set.

When the ADC clock source is something other than FRC, a SLEEP instruction causes the present conversion to be aborted and the ADC module is turned off, although the ADON bit remains set.

9.2.5 SPECIAL EVENT TRIGGER

An ECCP Special Event Trigger allows periodic ADC measurements without software intervention. When this trigger occurs, the GO/DONE bit is set by hardware and the Timer1 counter resets to zero.

Using the Special Event Trigger does not assure proper ADC timing. It is the user's responsibility to ensure that the ADC timing requirements are met.

See **Section 11.0 "Enhanced Capture/Compare/PWM Module"** for more information.

9.2.6 A/D CONVERSION PROCEDURE

This is an example procedure for using the ADC to perform an Analog-to-Digital conversion:

1. Configure Port:
   - Disable pin output driver (See TRIS register)
   - Configure pin as analog
2. Configure the ADC module:
   - Select ADC conversion clock
   - Configure voltage reference
   - Select ADC input channel
   - Select result format
   - Turn on ADC module
3. Configure ADC interrupt (optional):
   - Clear ADC interrupt flag
   - Enable ADC interrupt
   - Enable peripheral interrupt
   - Enable global interrupt**(1)**
4. Wait the required acquisition time**(2)**.
5. Start conversion by setting the GO/DONE bit.
6. Wait for ADC conversion to complete by one of the following:
   - Polling the GO/DONE bit
   - Waiting for the ADC interrupt (interrupts enabled)
7. Read ADC Result
8. Clear the ADC interrupt flag (required if interrupt is enabled).

Note 1:	The global interrupt can be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.
2:	See **Section 9.3 "A/D Acquisition Requirements"**.

TABLE 9-2: SUMMARY OF ASSOCIATED ADC REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ADCON0	ADFM	VCFG	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	0000 0000	0000 0000
ADCON1	—	ADCS2	ADCS1	ADCS0	—	—	—	—	-000 ----	-000 ----
ANSEL	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111
ANSELH	—	—	—	—	ANS11	ANS10	ANS9	ANS8	---- 1111	---- 1111
ADRESH	A/D Result Register High Byte								xxxx xxxx	uuuu uuuu
ADRESL	A/D Result Register Low Byte								xxxx xxxx	uuuu uuuu
INTCON	GIE	PEIE	T0IE	INTE	RABIE	T0IF	INTF	RABIF	0000 000x	0000 000x
PIE1	—	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	-000 0000	-000 0000
PIR1	—	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	-000 0000	-000 0000
PORTA	—	—	RA5	RA4	RA3	RA2	RA1	RA0	--xx xxxx	--uu uuuu
PORTB	RB7	RB6	RB5	RB4	—	—	—	—	xxxx ----	uuuu ----
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	--11 1111	--11 1111
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	—	—	—	—	1111 ----	1111 ----
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged, – = unimplemented read as '0'. Shaded cells are not used for ADC module.

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TABLE 12-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 11.0592 MHz			FOSC = 8.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	16665	300.0	0.00	15359	300.0	0.00	9215	300.0	0.00	6666
1200	1200	-0.01	4166	1200	0.00	3839	1200	0.00	2303	1200	-0.02	1666
2400	2400	0.02	2082	2400	0.00	1919	2400	0.00	1151	2401	0.04	832
9600	9597	-0.03	520	9600	0.00	479	9600	0.00	287	9615	0.16	207
10417	10417	0.00	479	10425	0.08	441	10433	0.16	264	10417	0	191
19.2k	19.23k	0.16	259	19.20k	0.00	239	19.20k	0.00	143	19.23k	0.16	103
57.6k	57.47k	-0.22	86	57.60k	0.00	79	57.60k	0.00	47	57.14k	-0.79	34
115.2k	116.3k	0.94	42	115.2k	0.00	39	115.2k	0.00	23	117.6k	2.12	16

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.01	3332	300.0	0.00	3071	299.9	-0.02	1666	300.1	0.04	832
1200	1200	0.04	832	1200	0.00	767	1199	-0.08	416	1202	0.16	207
2400	2398	0.08	416	2400	0.00	383	2404	0.16	207	2404	0.16	103
9600	9615	0.16	103	9600	0.00	95	9615	0.16	51	9615	0.16	25
10417	10417	0.00	95	10473	0.53	87	10417	0.00	47	10417	0.00	23
19.2k	19.23k	0.16	51	19.20k	0.00	47	19.23k	0.16	25	19.23k	0.16	12
57.6k	58.82k	2.12	16	57.60k	0.00	15	55.56k	-3.55	8	—	—	—
115.2k	111.1k	-3.55	8	115.2k	0.00	7	—	—	—	—	—	—

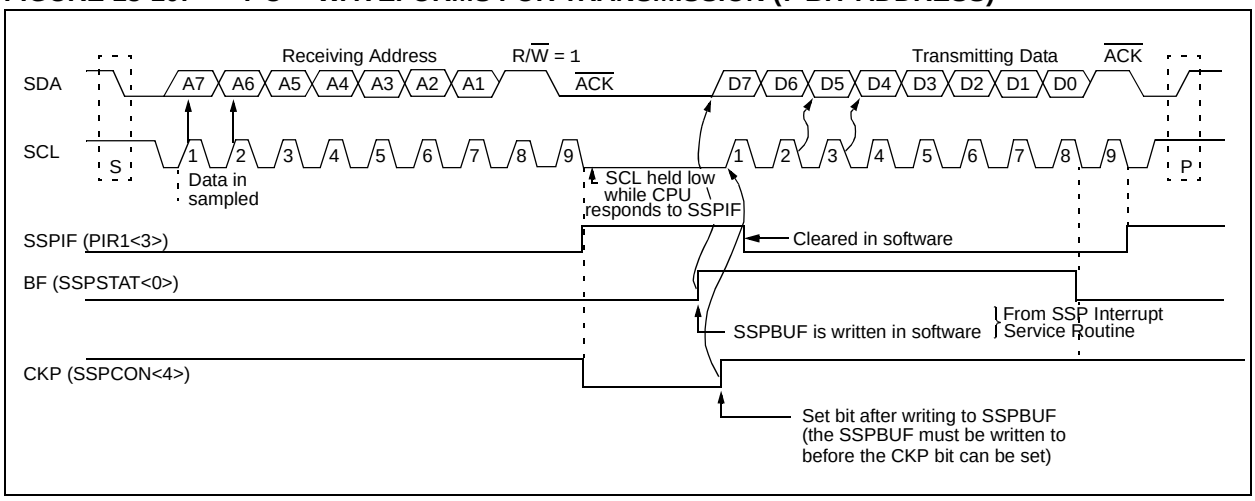
13.12.4 TRANSMISSION

When the R/$\overline{W}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{ACK}$ pulse will be sent on the ninth bit, and pin RB6/SCK/SCL is held low. The transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then, pin RB6/SCK/SCL should be enabled by setting bit CKP (SSPCON<4>). The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 13-10).

An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF must be cleared in software, and the SSPSTAT register is used to determine the status of the byte. Flag bit SSPIF is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the $\overline{ACK}$ pulse from the master receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not $\overline{ACK}$), then the data transfer is complete. When the $\overline{ACK}$ is latched by the slave, the slave logic is reset (resets SSPSTAT register) and the slave then monitors for another occurrence of the Start bit. If the SDA line was low ($\overline{ACK}$), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then pin RB6/SCK/SCL should be enabled by setting bit CKP.

FIGURE 13-10: I²C™ WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)



14.6 Power-Down Mode (Sleep)

The Power-Down mode is entered by executing a SLEEP instruction.

If the Watchdog Timer is enabled:

- WDT will be cleared but keeps running.
- $\overline{PD}$ bit in the STATUS register is cleared.
- $\overline{TO}$ bit is set.
- Oscillator driver is turned off.
- I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).

For lowest current consumption in this mode, all I/O pins should be either at V_{DD} or V_{SS}, with no external circuitry drawing current from the I/O pin and the comparators and CV_{REF} should be disabled. I/O pins that are high-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTA should be considered.

The $\overline{MCLR}$ pin must be at a logic high level.

Note:	It should be noted that a Reset generated by a WDT time-out does not drive $\overline{MCLR}$ pin low.

14.6.1 WAKE-UP FROM SLEEP

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from RA2/INT pin, PORTA change or a peripheral interrupt.

The first event will cause a device Reset. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device Reset. The $\overline{PD}$ bit, which is set on power-up, is cleared when Sleep is invoked. $\overline{TO}$ bit is cleared if WDT Wake-up occurred.

The following peripheral interrupts can wake the device from Sleep:

1. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
2. ECCP Capture mode interrupt.
3. A/D conversion (when A/D clock source is FRC).
4. EEPROM write operation completion.
5. Comparator output changes state.
6. Interrupt-on-change.
7. External Interrupt from INT pin.
8. EUSART Break detect, I^2C slave.

Other peripherals cannot generate interrupts since during Sleep, no on-chip clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up occurs regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction, then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

Note:	If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from Sleep. The SLEEP instruction is completely executed.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

14.6.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will not be cleared, the $\overline{TO}$ bit will not be set and the $\overline{PD}$ bit will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from Sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

15.2 Instruction Descriptions

ADDLW	Add literal and W
Syntax:	[*label*] ADDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the 8-bit literal 'k' and the result is placed in the W register.

ADDWF	Add W and f
Syntax:	[*label*] ADDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) → (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

ANDLW	AND literal with W
Syntax:	[*label*] ANDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the 8-bit literal 'k'. The result is placed in the W register.

ANDWF	AND W with f
Syntax:	[*label*] ANDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .AND. (f) → (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

BCF	Bit Clear f
Syntax:	[*label*] BCF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	0 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BSF	Bit Set f
Syntax:	[*label*] BSF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	1 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

BTFSC	Bit Test f, Skip if Clear
Syntax:	[*label*] BTFSC f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	skip if (f<b>) = 0
Status Affected:	None
Description:	If bit 'b' in register 'f' is '1', the next instruction is executed. If bit 'b' in register 'f' is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2-cycle instruction.

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MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Description: The contents of register 'f' is moved to a destination dependent upon the status of 'd'. If d = 0, destination is W register. If d = 1, the destination is file register 'f' itself. d = 1 is useful to test a file register since status flag Z is affected.

Words: 1

Cycles: 1

Example:

```
MOVF    FSR, 0
```

After Instruction
W = value in FSR register
Z = 1

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: $0 \le f \le 127$

Operation: (W) → (f)

Status Affected: None

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example:

```
MOVW    OPTION
F
```

Before Instruction
OPTION = 0xFF
W = 0x4F
After Instruction
OPTION = 0x4F
W = 0x4F

MOVLW **Move literal to W**

Syntax: [*label*] MOVLW k

Operands: $0 \le k \le 255$

Operation: k → (W)

Status Affected: None

Description: The 8-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.

Words: 1

Cycles: 1

Example:

```
MOVLW   0x5A
```

After Instruction
W = 0x5A

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Description: No operation.

Words: 1

Cycles: 1

Example:

```
NOP
```

16.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

16.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

17.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40° to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +6.5V
Voltage on $\overline{MCLR}$ with respect to Vss ..... -0.3V to +13.5V
Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)
Total power dissipation(1) ..... 800 mW
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ± 20 mA
Output clamp current, I_{OK} (Vo < 0 or Vo >V_{DD}) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA, PORTB and PORTC (combined) ..... 200 mA
Maximum current sourced PORTA, PORTB and PORTC (combined) ..... 200 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

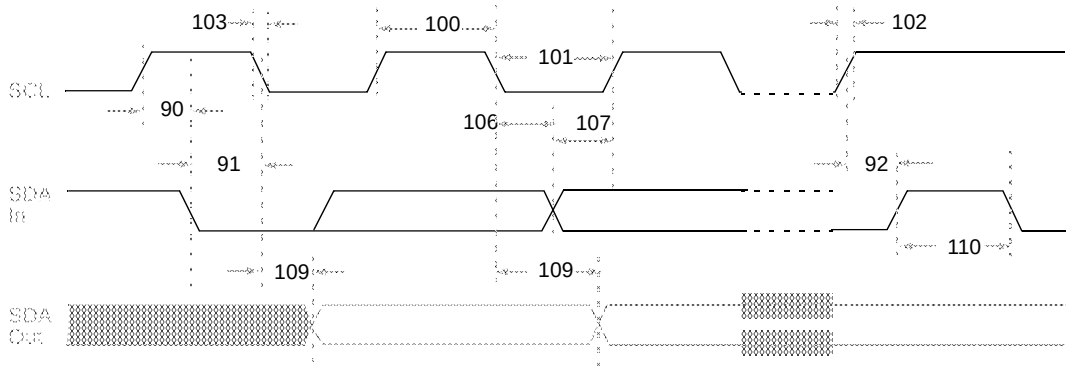
Note: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a “low” level to the $\overline{MCLR}$ pin, rather than pulling this pin directly to V_{SS}.

TABLE 17-13: I²C™ BUS START/STOP BITS REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ.	Max.	Units	Conditions
90*	TSU:STA	Start condition Setup time	100 kHz mode	4700	—	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	—		
91*	THD:STA	Start condition Hold time	100 kHz mode	4000	—	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	—		
92*	TSU:STO	Stop condition Setup time	100 kHz mode	4700	—	—	ns	
			400 kHz mode	600	—	—		
93	THD:STO	Stop condition Hold time	100 kHz mode	4000	—	—	ns	
			400 kHz mode	600	—	—		

* These parameters are characterized but not tested.

FIGURE 17-17: I²C™ BUS DATA TIMING



Note: Refer to Figure 17-3 for load conditions.

TABLE 17-15: A/D CONVERTER (ADC) CHARACTERISTICS:

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD01	NR	Resolution	—	—	10 bits	bit	
AD02	EIL	Integral Error	—	—	±1	LSb	VREF = 5.12V
AD03	EDL	Differential Error	—	—	±1	LSb	No missing codes to 10 bits VREF = 5.12V
AD04	EOFF	Offset Error	—	—	±1	LSb	VREF = 5.12V
AD04A			—	+1.5	+3.0	LSb	(PIC16F677 only)
AD07	EGN	Gain Error	—	—	±1	LSb	VREF = 5.12V
AD06 AD06A	VREF	Reference Voltage(3)	2.2 2.5	—	— VDD	V	 Absolute minimum to ensure 1 LSb accuracy
AD07	VAIN	Full-Scale Range	VSS	—	VREF	V	
AD08	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	
AD09*	IREF	VREF Input Current(3)	10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN.
			—	—	50	μA	During A/D conversion cycle

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

2: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

3: ADC VREF is from external VREF or VDD pin, whichever is selected as reference input.

4: When ADC is off, it will not consume any current other than leakage current. The power-down current specification includes any such leakage from the ADC module.

FIGURE 18-18: MAXIMUM WDT IPD VS. VDD OVER TEMPERATURE

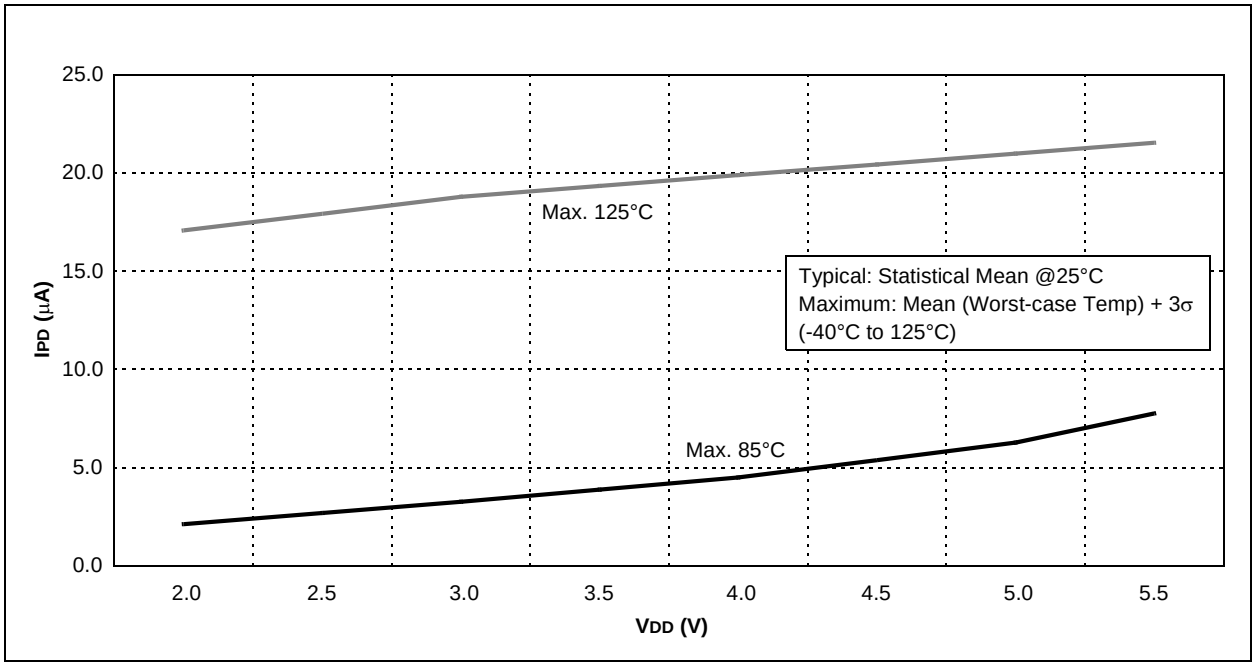


FIGURE 18-19: WDT PERIOD VS. VDD OVER TEMPERATURE